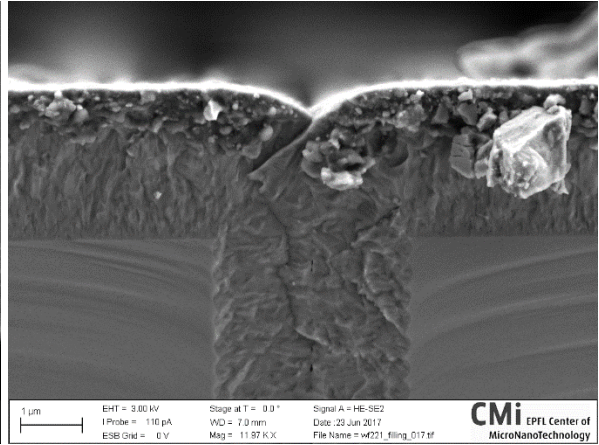
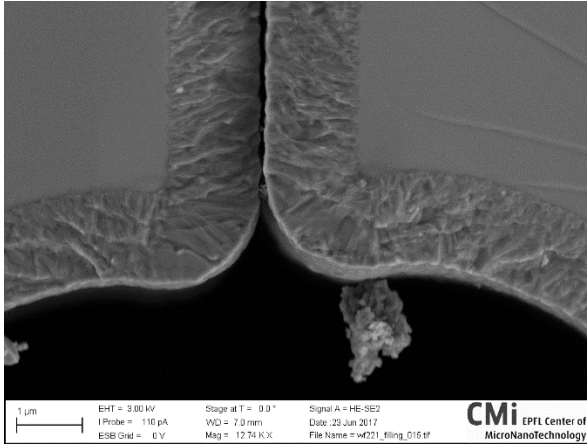


Membrane broken	He leak	Broken	No leak not broken	Membrane undulated
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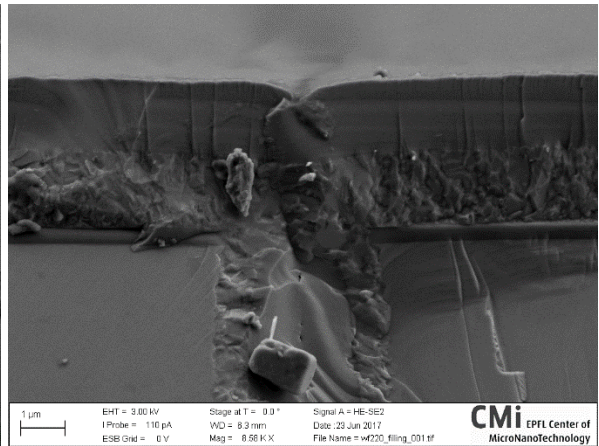
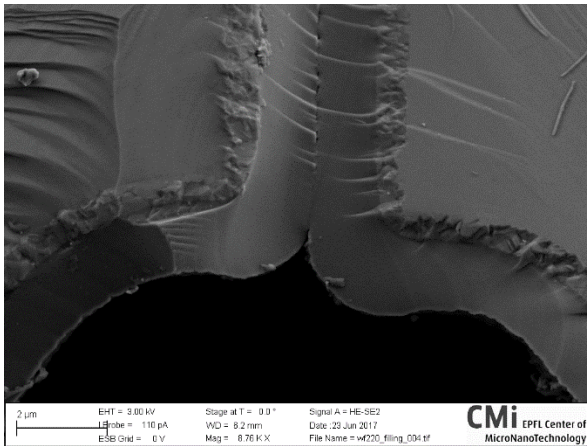
Table 1: Pressure at failure or maximum pressure reached

The inlet of Wf 219 were etched with the wafer glued with quickstick to a support wafer. After the etching and PR stripping, weird stripes were visible on some parts of the wafer and could not be removed by O2 plasma. The trench observation revealed that these stripes were due to PR not protecting the wafer probably because of overheating.

Wf221



Wf220



Wf214

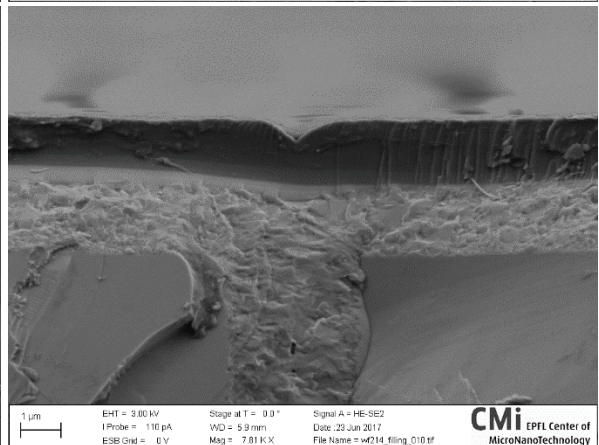
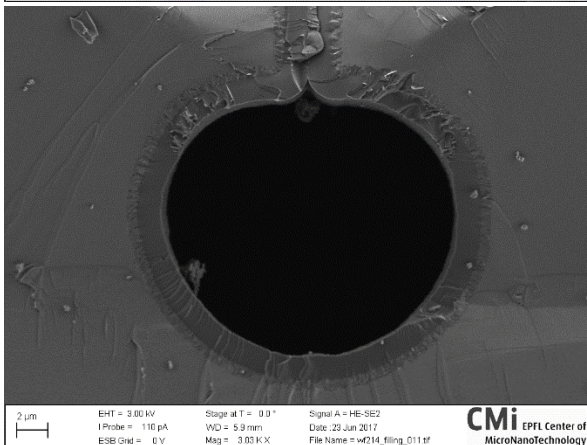


Figure 1: image of trench for three closing types. Wf 221: No oxide, no mask Wf 220: Oxide + mask Wf 214: Oxide, no mask

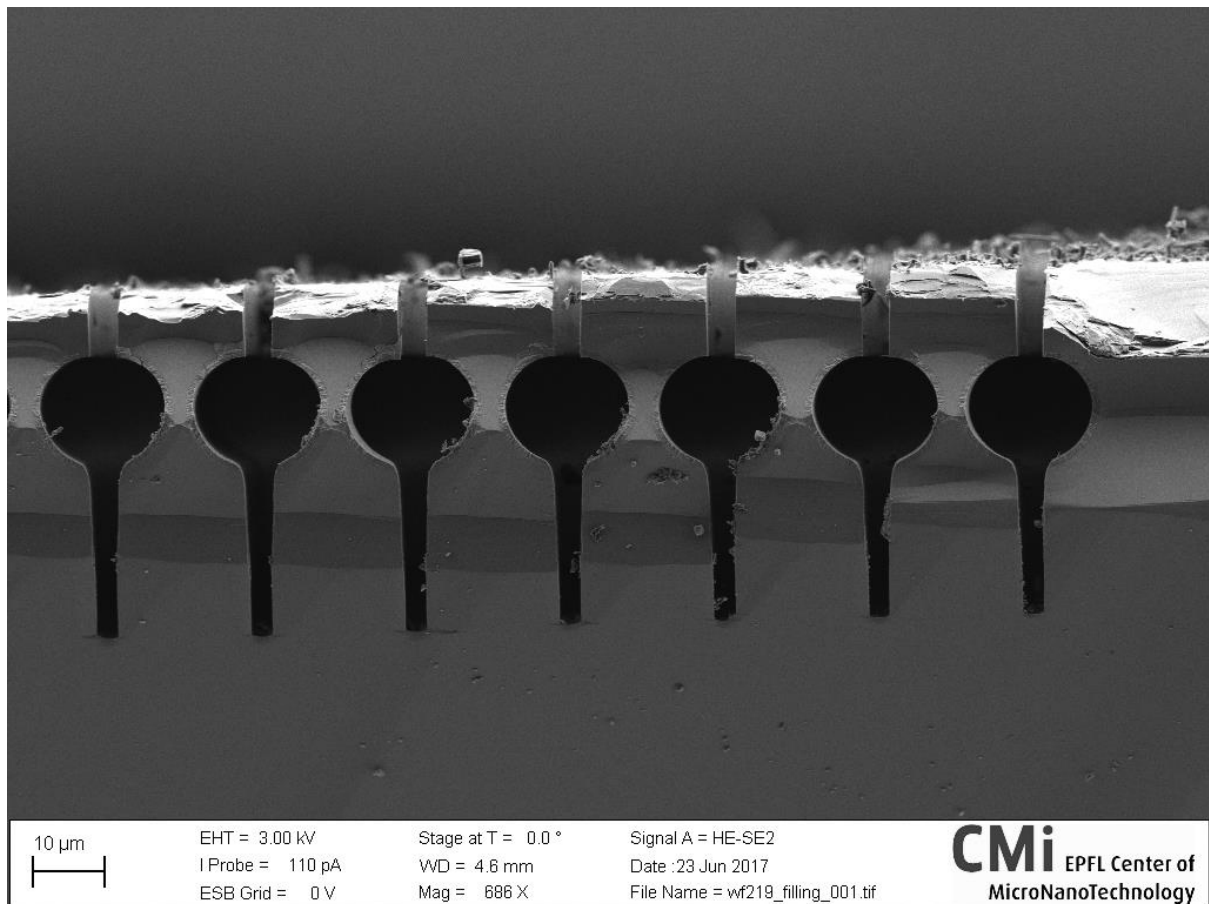


Figure 2: trench observation of Wf219: some parts of the sample have been exposed during the inlet etching